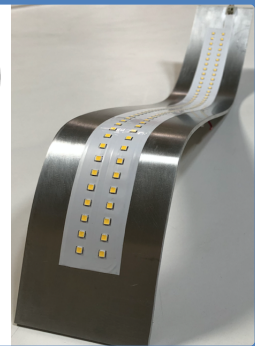


# CelLink LumiFlex™

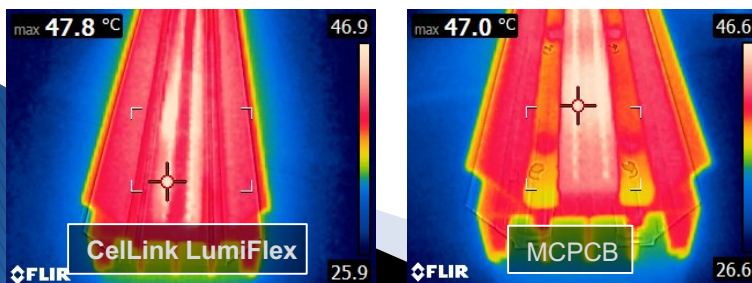
## MCPCB Performance in a Flexible Form Factor

- ▶ Thermal performance of MCPCBs
- ▶ Adhesive backing eliminates screws, screw holes and reduces board area
- ▶ Simplify heat sink design
- ▶ Enable higher lumens per foot in curved applications



Property	Measurement Type	Pressure Sensitive Adhesive (PSA)	Test Method
Thermal	Thermal Resistance	2.9 °C-cm <sup>2</sup> /W	ASTM 5470
	Thermal Conductivity	0.8 W/mK	ASTM 5470
Electrical	Breakdown Voltage	>2000V DC	ASTM D149
	Dielectric constant	2.4	ASTM D149
	UL Flammability Rating	V-0	UL 94
Mechanical	Peel Strength@25C, initial (20 PSI application pressure)	0.8 N/mm	Instron 180° peel from powder-coat paint surface
	Peel Strength @25C, after 120 hrs aging at 90C	2.9 N/mm	Instron 180° peel from powder-coat paint surface
	Minimum Bend Radius, static	2 mm	CelLink internal
General	Color	White (>95% reflectance, 400-700 nm)	Spectrophotometer with Integrating Sphere
	Operating Temperature Range	-40C to +90 °C	UL 8750; USCAR T2; higher temp. configurations available upon request
	Maximum Recommended Solder Temperature	185 °C, 90s	higher solder temp. configurations available upon request
	Surface Finish	Entek Cu-56 OSP	

CelLink LumiFlex performs to within 1°C/W of state-of-the-art MCPCBs



For more information:

- ▶ Manufactured by CelLink in San Carlos, CA, USA
- Distributed by NRC Electronics
- ▶ Michael Thomas, [m.thomas@nrcelectronics.com](mailto:m.thomas@nrcelectronics.com)

